

## Patent Abstracts of Japan

PUBLICATION NUMBER : 2000349111  
PUBLICATION DATE : 15-12-00

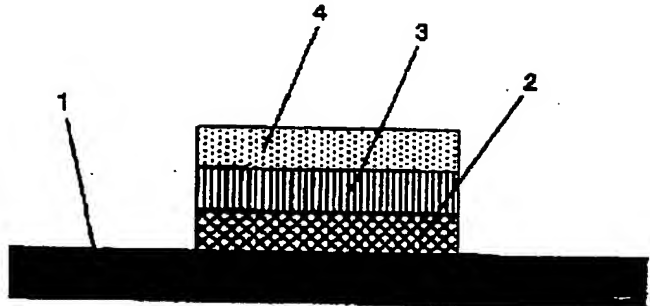
APPLICATION DATE : 03-06-99  
APPLICATION NUMBER : 11157103

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INT.CL. : H01L 21/60

TITLE : ELECTRODE FOR SOLDER BONDING



**ABSTRACT :** PROBLEM TO BE SOLVED: To provide the structure of an electrode for a solder bonding wherein, even in the case where a solder bump is formed using a lead free solder, the disappearance of the electrode (barrier metal layer) due to electrode corrosion is not caused.

**SOLUTION:** The structure of a barrier metal layer of an electrode for a solder bonding is formed into a laminated structure formed by laminating an electroless plating nickel layer 3 and an electrolytic plating nickel layer 4. First, the layer 3 is formed on a base layer (feeding layer) 2 and the layer 4 is formed on the above layer 3 in contact with the layer 3. By this structure, the good wettability of solder of the electrode with the layer 2 is ensured, the reliability of the soldered portion to the layer 2 is ensured and at the same time, at the time of the formation of a solder bump, the electrode (barrier metal layer) can be prevented from being disappeared by electrode corrosion.

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